

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An apparatus comprising:

an integrated circuit die;

an integrated circuit package coupled to the integrated circuit die;

mold compound in contact with the integrated circuit die and the integrated circuit package;

a first solder ball in contact with the integrated circuit package;

a second integrated circuit package; and

a second solder ball, wherein the second solder ball is in contact with the second integrated circuit package, and in contact with the mold compound,

wherein the first solder ball comprises a greater radius and a greater circumference than the second solder ball,

wherein a first portion of the first solder ball is in contact with the mold compound, wherein a second portion of the first solder ball is not in contact with the mold compound, wherein the mold compound defines an opening, wherein the second portion of the first solder ball is recessed beneath the opening, wherein a third portion of the first solder ball is in contact with the integrated circuit package, and wherein the second solder ball is in contact with the first solder ball within the opening.

2. (Previously presented) An apparatus according to Claim 1, wherein the second portion is an upper portion of the first solder ball and the third portion is a lower portion of the first solder ball.

3. (Cancelled)

4. (Previously presented) An apparatus according to Claim 1, wherein the second integrated circuit package is in contact with the mold compound.

5. (Previously presented) An apparatus according to Claim 1 further comprising:

a second integrated circuit die in contact with the second integrated circuit package;

second mold compound in contact with the second integrated circuit die and the second integrated circuit package; and

a third solder ball coupled to the second integrated circuit package,

wherein a first portion of the third solder ball is in contact with the second mold compound, and wherein a second portion of the third solder ball is not in contact with the second mold compound, wherein the second mold compound defines a second opening, wherein the second portion of the third solder ball is recessed beneath the second opening, and wherein a third portion of the third solder ball is in contact with the second integrated circuit package.

6. (Previously presented) An apparatus according to Claim 5, further comprising:

a third integrated circuit package;

a fourth solder ball coupled to the third integrated circuit package,

wherein the fourth solder ball is coupled to the third solder ball within the second opening.

7. (Original) An apparatus according to Claim 1, further comprising:

a second integrated circuit die coupled to the integrated circuit die, in contact with the mold compound, and electrically coupled to the integrated circuit package.

8. (Currently Amended) An apparatus comprising:

an integrated circuit package substrate;

a plurality of integrated circuit die coupled to the integrated circuit package substrate;

mold compound in contact with the plurality of integrated circuit die and the integrated circuit package substrate;

a first solder ball in contact with the integrated circuit package substrate and electrically coupled to one of the plurality of integrated circuit die;

a second integrated circuit package;

a second solder ball, wherein the second solder ball is in contact with the second integrated circuit package, and in contact with the mold compound,

wherein the first solder ball comprises a greater radius and a greater circumference than the second solder ball, a second solder ball in contact with the second integrated circuit package,

wherein a first portion of the first solder ball is in contact with the mold compound, wherein a second portion of the first solder ball is not in contact with the mold compound, wherein the mold compound defines an opening, wherein the second portion of the first solder ball is recessed beneath the opening, wherein a third portion of the first solder ball is in contact with the integrated circuit package substrate, and wherein the second solder ball is in contact with the first solder ball within the opening.

9. (Previously presented) An apparatus according to Claim 8, further comprising:

die attach material disposed between the first face of each of the plurality of integrated circuit die and the integrated circuit package substrate.

10. (Previously presented) An apparatus according to Claim 8, further comprising:

a second integrated circuit die in contact with the integrated circuit die, in contact with the mold compound, and electrically coupled to the integrated circuit package.

11. - 14. (Cancelled)

15. (Currently Amended) A system comprising:

an integrated circuit die;

an integrated circuit package in contact with the integrated circuit die;

mold compound in contact with the integrated circuit die and the integrated circuit package; and

a first solder ball coupled to the integrated circuit package;

a second integrated circuit die;

a second integrated circuit package;

a second solder ball, wherein the second solder ball is in contact with the second integrated circuit package, and in contact with the mold compound;

~~a second solder ball in contact with the second integrated circuit package; and~~

a double data rate memory electrically coupled to the integrated circuit die,

wherein the first solder ball comprises a greater radius and a greater circumference than the second solder ball,

wherein a first portion of the first solder ball is in contact with the mold compound, wherein a second portion of the first solder ball is not in contact with the mold compound, wherein the mold compound defines an opening, wherein the second portion of the first solder ball is recessed beneath the opening, wherein a third portion of the first solder ball is in contact with the integrated circuit package, and wherein the second solder ball is in contact with the first solder ball within the opening.

16. (Cancelled)

17. (Previously presented) A system according to Claim 15, wherein the second integrated circuit package is in contact with the mold compound.

18. (Previously presented) A system according to Claim 15, further comprising:

a third integrated circuit die in contact with the integrated circuit die, in contact with the mold compound, and electrically coupled to the integrated circuit package.

19. (Original) A system according to Claim 15, further comprising:

a motherboard electrically coupled to the integrated circuit die and to the memory.